

INFRARED TRANSMISSIVE INTEGRATED CIRCUIT SOCKET CAP

Abstract of the Disclosure

A cap may be provided over the hinged cover of an integrated circuit socket to be surface mounted to a printed circuit board. The cap may protect the socket prior to the insertion of the integrated circuit. It may also facilitate the surface mounting of the socket to a printed circuit board. It may do so in at least two ways. The cap may facilitate convective heating by the provision of a series of openings in the cap. The cap may also be infrared transmissive so that infrared radiation from a surface mount oven passes through the cap to heat the socket. As a result, in some embodiments, better reflow is achieved and higher solder ball reliability may result.